



SDI FINAL EVALUATION FORM 1.1

PART 1:

Journal Name:	Physical Science International Journal
Manuscript Number:	Ms_PSIJ_29024
Title of the Manuscript:	Influence of Annealing Temperature on the Physical Properties of Polycrystalline Cu ₂ SnSe ₃ Thin Films Prepared by Thermal Vacuum Evaporation Technique
Type of Article:	Original Research Article

PART 2:

FINAL EVALUATOR'S comments on revised paper (if any)	Authors' response to final evaluator's comments
<p>Experimental line 2 delete the second point after together. The authors told about polycrystal but they don't show any X ray diffraction pattern.</p> <p>The stoichiometric composition of source material was around 26% Cu, 25% Sn, and 49% Se, however from initial composition has not the relation Cu₂SnSe₃. Review the atomic composition and the table No.1 because if you considered as example: Table No.1 at 200°C. %at Sn 10.86 as base 1, the %at Cu and %at Se are 32.39 and 56.75. Divide by 10.86</p> <p>Previous corrections were not realized</p> <p>Experimental Paragraph 1 line 2 delete the second point, after were mixed together..</p> <p>3.1 Scanning Electron Microscopy (SEM) Paragraph 1 line 6 To change times by x. See word document.</p>	<p>Line 2 removed - The wide range of magnification makes it suitable for investigation of microstructure of Cu₂SnSe₃ thin films.</p> <p>The EDX analysis revealed that the as-deposited and annealed thin films of Cu₂SnSe₃ are found to contain the nearly stoichiometric composition calculated earlier where atomic percentage for each element Cu, Sn, and Se corresponding to 26%, 25%, and 49%. However, yes we agreed and already mentioned that the composition comes with ratio (2:1:3) which is 33.33, 16.67 and 50%. Thank you for the clarification. But this techniques proved that there are limitation occurs while using thermal evaporation and already mentioned in other journal.</p> <p>Changed to mixed together.</p> <p>Times changed to x</p>